COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.
ASSEMBLY VARIANT: [No Variations]

<table>
<thead>
<tr>
<th>PCB VIEWED FROM TOP SIDE</th>
<th>BOARD #: TIDM-TM4C129USBHS</th>
<th>SUN REV: Not In VersionControl</th>
</tr>
</thead>
<tbody>
<tr>
<td>LAYER NAME = Bottom Overlay</td>
<td>TID #: TIDM-TM4C129USBHS</td>
<td></td>
</tr>
<tr>
<td>PLOT NAME = Solder SideAssembly Drawing</td>
<td>GENERATED : 9/9/2016 3:18:31 PM</td>
<td>TEXAS INSTRUMENTS</td>
</tr>
</tbody>
</table>
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